

ABSTRACT

Silicone resin compositions comprising (A) a silicone
5 resin having at least two alkenyl groups bonded to silicon
atoms in a molecule, (B) an organohydrogensilane and/or
organohydrogenpolysiloxane having at least two hydrogen atoms
bonded to silicon atoms in a molecule, and (C) an addition
10 reaction catalyst cure into transparent products having heat
resistance and discoloration resistance and are used with LED
devices for the purposes of protection, encapsulation,
bonding, wavelength alteration or adjustment, and lens
formation of LED devices.